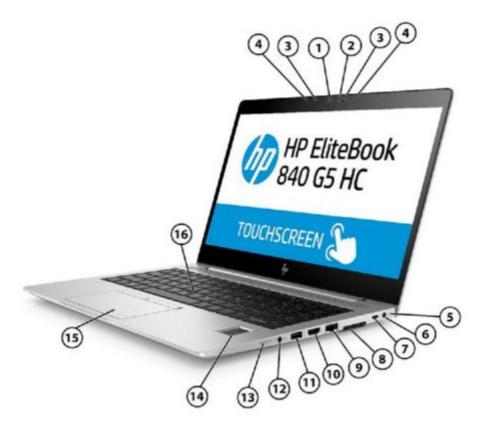


Overview

HP EliteBook 840 G5 Healthcare Edition Notebook PC



- 1. Webcam and IR Camera
- 2. Webcam LED
- 3. Internal microphones
- 4. IR Camera LEDs
- 5. Charging light
- 6. Power connector
- 7. USB Type-CTM with ThunderboltTM
- 8. Docking connector

Left

- 9. Ethernet port
- 10. HDMI port (Cable not included)
- 11. USB 3.1 Gen 1 port
- 12. Audio combo jack
- 13. SIM card slot¹
- 14. Fingerprint reader (Select models)
- 15. Clickpad and RFID/NFC tap area (select models)
- 16. Pointstick
- 1. All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug

Overview



Right

- Indicator LEDs:
 Power ligh
 Wireless light
 Storage usage light
- 2. Smartcard Reader (Select models)
- 3. USB 3.1 Gen 1 charging port

- 4. Security Lock slot (Lock sold separately)
- 5. Power button

Overview

AT A GLANCE

- Engineered for sanitization with germicidal wipes every shift, every day (please see Cleaning Instructions for supported wipes)^{4,5}
- Integrated single sign-on badge capability¹
- Integrated FIPS-201 compliant fingerprint reader for electronic prescribing of medication¹
- EN60601-1-2:2015 compliant for EMI safety
- World class security and manageability with HP Sure Start Gen 4, HP Sure View, HP Sure Run, HP Sure Restore, HP Sure Click, HP MIK, HP WorkWise, IR Camera, SmartCard Reader¹, Fingerprint reader¹, Self-encrypting SSDs¹, and Absolute Computrace embedded¹
- HP Sure View 14.0" 700nit FHD IPS display
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles²
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke
- Experience telemedicine with an HD camera and Infrared camera with multi-array noise-cancelling microphones and loud top-firing speakers (74dB)
- Designed to support all HP docking options including HP's traditional Ultraslim mechanical dock and all-new ThunderboltTM dock.¹
- Choice of 8th Generation Intel® Core[™] i5, i7 Quad-core Processors and 7th generation Intel® Core[™] i5 Dual-core Processors
- Preinstalled with Windows 10 versions or FreeDOS
- AMD Radeon RX540 discrete graphics with 2 GB GDDR5 video memory¹
- HP Long Life Battery
- MIL-STD testing³
- 1. Sold separately or as an optional feature.
- 2. Recharges your battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

The Long Life battery will have same 1-year or 3-year limited warranty as the platform. HP Long-Life Rechargeable batteries are designed to last 1,000 battery cycles based on typical use over a 3-yr period.

3. MIL-STD-810G testing is conducted on all HP EliteBook products. Testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Features

PRODUCT NAME

HP EliteBook 840 G5 Healthcare Edition Notebook PC

OPERATING SYSTEM

Preinstalled

Windows 10 Pro 64¹ Windows 10 Home 64¹ FreeDOS 2.0

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purch updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http:

PROCESSORS

Intel® CoreTM i5-7200U with Intel® HD Graphics 620 (2.5 GHz base frequency, up to 3.1 GHz with Intel® Turbo Boost Technolog Intel® CoreTM i5-7200U with AMD RadeonTM RX 540 with 2 GB GDDR5 dedicated (2.5 GHz base frequency, up to 3.1 GHz with Intel® CoreTM i5-7300U vProTM processor with Intel® HD Graphics 620 (2.6 GHz base frequency, up to 3.5 GHz with Intel® Turbo Intel® CoreTM i5-7300U vProTM processor with AMD RadeonTM RX 540 with 2 GB GDDR5 dedicated (2.6 GHz base frequency, up Intel® CoreTM i5-8250U with Intel® UHD Graphics 620 (1.6 GHz base frequency, up to 3.4 GHz with Intel® Turbo Boost Technolo Intel® CoreTM i5-8250U with AMD RadeonTM RX 540 with 2 GB GDDR5 dedicated (1.6 GHz base frequency, up to 3.6 GHz with Intel® Turbo Intel® CoreTM i5-8350U vProTM processor with Intel® UHD Graphics 620 (1.7 GHz base frequency, up to 3.6 GHz with Intel® Turbo Intel® CoreTM i7-8550U with Intel® UHD graphics 620 (1.8 GHz base frequency, up to 4 GHz with Intel® Turbo Boost Technology Intel® CoreTM i7-8550U with AMD RadeonTM RX 540 with 2 GB GDDR5 dedicated (1.8 GHz base frequency, up to 4 GHz with Intel® Turbo Intel® CoreTM i7-8650U vProTM processor with Intel® UHD graphics 620 (1.9 GHz base frequency, up to 4.2 GHz with Intel® Turbo Intel® CoreTM i7-8650U vProTM processor with AMD RadeonTM RX 540 with 2 GB GDDR5 dedicated (1.9 GHz base frequency, up to 4.2 GHz with Intel® Turbo Intel® CoreTM i7-8650U vProTM processor with AMD RadeonTM RX 540 with 2 GB GDDR5 dedicated (1.9 GHz base frequency, up to 4.2 GHz with Intel® Turbo Intel® CoreTM i7-8650U vProTM processor with AMD RadeonTM RX 540 with 2 GB GDDR5 dedicated (1.9 GHz base frequency, up

Processor Family

7th Generation Intel® CoreTM i5 processor (i5-7300, i5-7200 models) 8th Generation Intel® CoreTM i5 processor (i5-8350, i5-8250 models) 8th Generation Intel® CoreTM i7 processor (i7-8650, i7-8550 models)

- 2. Multicore is designed to improve performance of certain software products. Not all customers or software applications will and your hardware and software configurations. Intel's numbering branding and/or naming is not a measurement of higher performance mode; processors will run at lower speeds in battery optimization mode.
- 4. NOTE: In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on http://www.support.hp.com.

CHIPSET



Features

Integrated with processor

GRAPHICS

Integrated

Intel® HD Graphics 620⁵ Intel® UHD Graphics 620⁵

Discrete

AMD RadeonTM RX 540 (2 GB GDDR5 dedicated)^{6,7} Support HD decode, DX12, HDMI 1.4b^{5,8}

- 5. HD content required to view HD images.
- 6. Sold separately or as an optional feature.
- 7. AMD Dynamic Switchable Graphics technology requires an Intel processor, plus an AMD RadeonTM discrete graphics configu discrete graphics video and display features may not be supported on all systems (e.g. OpenGL applications will run on the in 8. HDMI cable sold separately.

DISPLAY

Touch

HP Sure View Integrated Privacy Screen 35.6 cm (14") diagonal FHD IPS LED-backlit touch screen with Corning® Gorilla® Glass

HDMI 1.4b

Supports resolution up to 4k @ 24Hz

Displays support

Supports 2 independent displays when on the HP Ultraslim Dock - Max. resolution = 2.5K @ 60Hz (DP1) & 2.5K @ 60Hz (DP2) Supports 2 independent displays when on the HP ThunderboltTM Dock G2 - Max. resolution = 4K @ 60Hz (DisplayPort) & 4K @ 60Hz (ThunderBolt)

- 5. HD content required to view HD images.
- 6. Sold separately or as an optional feature.
- 9. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

Features

Primary M.2 Storage

128 GB SATA-3 SS TLC¹⁰
256 GB PCIe NVMe Value SS TLC¹⁰
256 GB PCIe Gen3x4 NVMe SS TLC¹⁰
256 GB SATA-3 SS TLC Opal 2¹⁰
360 GB PCIe Gen3x4 NVMe SS TLC (Intel®) ¹⁰
512 GB PCIe Gen3x4 NVMe SS TLC¹⁰
512 GB PCIe Gen3x4 NVMe SS TLC Opal 2¹⁰
512 GB SATA-3 SS TLC FIPS-140-2¹⁰
1 TB PCIe Gen3x4 NVMe SS TLC¹⁰

10. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 1

MEMORY

Maximum Memory

32 GB DDR4-2400 SDRAM¹¹

Memory

32 GB DDR4-2400 SDRAM (2 X 16 GB)¹¹
16 GB DDR4-2400 SDRAM (1 X 16 GB)¹¹
16 GB DDR4-2400 SDRAM (2 X 8 GB)¹¹
8 GB DDR4-2400 SDRAM (1 x 8 GB)¹¹
8 GB DDR4-2400 SDRAM (2 x 4 GB)¹¹
4 GB DDR4-2400 SDRAM (1 x 4 GB)¹¹

Memory Slots

2 SODIMM Both slots are upgradeable System runs at 2133 for Intel® 7th generation processors System runs at 2400 for Intel® 8th generation processors Supports Dual Channel Memory.

11. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to e

NETWORKING/COMMUNICATIONS



Features

WLAN

Intel® Dual Band Wireless-AC 8265 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 4.2 Combo, vPro^{TM12} Intel® Dual Band Wireless-AC 8265 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 4.2 Combo, non-vPro^{TM12} Realtek RTL8822BE 802.11ac (2x2) Wi-Fi® and Bluetooth® 4.2 Combo, non-vPro^{TM12}

WWAN

HP lt4132 LTE/HSPA+ w/GPS M.2¹³ Intel® XMMTM 7360 LTE-Advanced¹³

NFC

NXP NPC300 Near Field Communication Module

Miracast

Native Miracast Support¹⁴

Ethernet

Intel® I219-LM 10/100/1000 GbE, vPro^{TM15} Intel® I219-V 10/100/1000 GbE, non-vPro^{TM15}

RFID

Ritani RFIdeas HF/LF RFID Read SE Module without SE Security Access Module (SE SAM)¹⁶

- 12. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.
- 13. WWAN module requires separately purchased service contract. Check with service provider for coverage and availability in on all products, in all regions.
- 14. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast.
- 15. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, an network infrastructure is required.
- 16. SE Security Access Module (SE SAM) is a separate hardware SIM inserted into the RFID reader and is required to support SE

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen Integrated Multi Array Microphones (with World-facing 3rd mic) 2 Integrated Stereo Speakers

Camera

720p HD and IR webcam supporting Wide Dynamic Range⁵

5. HD content required to view HD images.



Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Collaboration Keyboard, backlit, dual point, spill resistant with drain, with HP Dura Keys

Pointing Device

Clickpad with multi-touch gestures enabled, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

F1 - Display Switching

F2 - Privacy

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Backlit Toggle

F10 - numlk

F11 - Wireless

F12 - Calendar

Share/Present

Call Answer

Call End

Hidden Fuction Keys

Fn+R - Break

Fn+S - Sys Rq

Fn+C - Scroll Lock

SOFTWARE AND SECURITY

Preinstalled Software

BIOS

HP BIOSphere Gen4¹⁷

HP DriveLock & Automatic DriveLock

BIOS Update via Network

Master Boot Record Security

Power On Authentication

Secure Erase¹⁸

Absolute Persistence Module¹⁹

Pre-boot Authentication

HP Wireless Wakeup

Software

Features

HP Easy Clean⁴²

HP Native Miracast Support¹⁴

HP LAN-Wireless Protection

HP Velocity

HP 3D DriveGuard

HP ePrint Driver + JetAdvantage²⁰

HP Hotkey Support - CMIT

HP Recovery Manager

HP Jumpstart

HP Support Assistant²¹

HP Noise Cancellation Software

HP PhoneWise²⁸

Buy Office

Manageability Features

HP Driver Packs²²

HP System Software Manager (SSM)

HP BIOS Config Utility (BCU)

HP Client Catalog

HP Manageability Integration Kit Gen2²³

Ivanti Management Suite²⁴

Client Security Software

HP Client Security Suite Gen4²⁵ including:

HP Security Manager²⁶ (including Credential Manager, HP Password Manager, HP Spare Key)

FIPS-201 Compliant Fingerprint Sensor

HP Fingerprint Sensor³⁰

HP Device Access Manager

HP Power On Authentication

Microsoft Defender²⁷

Security Management

Secure Erase¹⁸

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)

SATA 0,1 port disablement (viaBIOS)

RAID configurations³¹

Serial, USB enable/disable (viaBIOS)

Power-on password (viaBIOS)

Setup password (viaBIOS)

Support for chassis padlocks and cable lock devices

Integrated hood sensor

HP Sure Click³²

HP Sure Start Gen4²⁹

HP Sure Run³³

Features

HP Sure Recover³⁴

TPM

Model: Infineon SLB9670 Version: 7.62.3126.0 Revision: TPM 2.0

FIPS 140-2 Compliant: Yes (select models only)

Smartcard Reader

Model number: Alcor AU9560 FIPS 201 Compliant: Yes

Fingerprint Sensor

HP Fingerprint Sensor³⁰

FIPS-201 compliant fingerprint reader

IPv6 Certification:

Yes

MD5 Hash: Please follow the instructions below to access MD5 Hash.

Log-on to http://hp.com/support, enter your product name, select software and drivers, select OS, select driver. After select the appropriate "SOFTPAQ MD5:"? Field

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?:

Yes

UEFI version: 2.5

- 14. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players t information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast.
- 17. HP BIOSphere Gen4 features may vary depending on the PC platform and configurations requires Windows and 8th Gen Int
- 18. Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88.
 19. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptic
- Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/cithe Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorizatior 20. HP ePrint Drive requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of Print times and connection speeds may vary.
- 21. HP Support Assistant requires Windows and Internet access.
- 22. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 23. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.h
- 24. Ivanti Management Suite subscription required.
- 25. HP Client Security Suite Gen 4 requires Windows and Intel® or AMD 8th generation processors.
- 26. HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be suppo
- 27. Microsoft Defender Opt in and internet connection required for updates.
- 28. HP PhoneWise Client is only available on select platforms. For supported platforms and HP PhoneWise system requirement
- 29. HP Sure Start Gen4 is available on HP EliteBook products equipped with Intel® 8th generation processors Optional in front
- 30. HP Fingerprint Sensor sold separately or as an optional feature.
- 31. RAID configuration is optional and does require a second hard drive.
- 32. HP Sure Click is available on select HP platforms and supports Microsoft® Internet Explorer and ChromiumTM. Check http://
- 33. HP Sure Run is available on HP Elite products equipped with Intel® or AMD® 8th generation processors
- 34. HP Sure Recover is available on HP Elite PCs with 8th generation Intel® or AMD processors and requires an open, wired net
- 42. HP Easy Clean requires Windows 10 RS3 and will disable the keyboard, touchscreen, and touchpad only. Ports are not disal

Features

POWER

Power Supply

HP Smart 45W External AC power adapter, 2-prong (Japan only)³⁵ HP Smart 65W External AC power adapter³⁵ HP Smart 65W EM External AC power adapter³⁵ HP USB Type-CTM 65W External AC power adapter³⁵

Primary Battery

HP Long Life 3-cell, 50 Wh Li-ion³⁶

Power Cord

2-wire plug - 1.0m (Japan only)³⁵ 3-wire plug - 1.0m³⁵ 3-wire plug - 1.8m³⁵ Duckhead power cord - 1.0m³⁵ Duckhead power cord - 1.8m³⁵

Battery Life

MobileMark 2014 run time: Sharing mode: 11 hours 15 minutes Privacy mode: 9 hours³⁷

- 35. Availability may vary by country.
- 36. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 37. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded appl naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Weight

Starting at 3.59 lb (touch)³⁸ Starting at 1.63 kg (touch)³⁸

Dimensions (w x d x h)

12.84 x 9.22 x 0.71 in 326 x 234.3 x 18.05 mm

38. Weight will vary by configuration.

PORTS/SLOTS

Features

Ports

- 1 ThunderboltTM (USB Type-CTM connector)
- 2 USB 3.1 Gen 1 (1 charging)
- 1 HDMI 1.4b⁸
- 1 RJ-45
- 1 Docking connector
- 1 Headphone/microphone combo
- 1 AC power
- SIM card slot
- Smartcard reader⁶
- 8. HDMI cable sold separately.
- 6. Sold separately or as an optional feature.

ENVIRONMENTAL & INDUSTRY

Environmental Data	Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® US Federal Energy Management Program (FEMP) EPEAT Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar energy accessory at http://www.hp.com/go/options. TCO or TCO Certified Edge			
	System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook"?.			
	Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
	Normal Operation (Sort idle)	8.24 W	8.11 W	7.97 W	
	Normal Operation (Long idle)	3.95 W	3.41 W	3.46 W	
	Sleep	0.85 W	0.88 W	0.85 W	
	Off	0.50 W	0.53 W	0.50 W	
		Note: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.			
	Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	

Features

Normal Operation (Short idle)	28 BTU/hr	28 BTU/hr	27 BTU/hr	
Normal Operation (Long idle)	14 BTU/hr	12 BTU/hr	12 BTU/hr	
Sleep	3 BTU/hr	3 BTU/hr	3 BTU/hr	
Off	2 BTU/hr	2 BTU/hr	2 BTU/hr	
	*NOTE: Heat dissipation is cal service level is attained for or		sured watts, assuming the	
Declared Noise	Sound Power		Sound Pressure	
Emissions	(L _{WAd} , bels)		(L _{pAm} , decibels)	
(in accordance with ISO 7779 and ISO 9296)				
Typically Configured - Idle	2.9		16	
Fixed Disk - Random writes	3.3		22	
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:			
	 3 USB ports 1 PC card slot (type I/II) 1 ExpressCard/54 slot 1 IEEE 1394 Port 2 SODIMM memory slots Optional expansion base docking station 1 multi-bay II storage port Interchangeable HDD?? Spare parts are available throughout the warranty period and or for up to "5"? years after the end of production.			
Batteries	"This battery(s) in this produ	uct comply with EU Direc	ctive 2006/66/EC	
Batteries used in the product do not contain: Mercury greater the1ppm by weight				
	Cadmium greater than 20ppm by weight			
	Battery size: CR2032 (coin	cell)		
	Battery type: Lithium"			
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). 			

Features

	< Gold > I Plastics p ISO11469 This prod This prod life.	uct is in compliance with the IEEE 1680 (EPEAT level, see www.epeat.net arts weighing over 25 grams used in the product and ISO1043. uct contains 0.0% post-consumer recycled plastiuct is 93.6% recycle-able when properly disposed	are marked per ic (by wt.) d of at end of
Packaging Materials	External:	PAPER/Corrugated	357 g
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	66 g
		PLASTIC/Polypropylene - PP	4 g
	The pleatic per	PLASTIC/Polyethylene low density - LDPE	15 g
		ckaging material contains at least 0.0% recycled I paper packaging materials contains at least 80%	
	content.	paper packaging materials contains at least oo.	70 Tecycled
Material Usage	limits (refer to the http://www.hp.c	es not contain any of the following substances in ex ne HP General Specification for the Environment at om/hpinfo/globalcitizenship/environment/pdf/gse	
Dackaging Heago	 Asbestos Certain Azo Colorants Certain Brominated Flame Retardants - may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel - finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) - except for wires and cables, has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) 		
Packaging Usage	packaging: • Eliminate in packagii • Eliminate io Design packagii	e guidelines to decrease the environmental impact the use of heavy metals such as lead, chromium, m ng materials. the use of ozone-depleting substances (ODS) in pack ckaging materials for ease of disassembly. the use of post-consumer recycled content materia	ercury and cadmium

Features		
		 Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
	End-of-life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
		The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
	HP, Inc. Corporate	For more information about HP's commitment to the environment:
	Environmental Information	Global Citizenship Report
		http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
		Eco-label certifications
		http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
		ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warrant http://www.hp.com/go/cpc.

39. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geo www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated t rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your

CLEANING INSTRUCTIONS

If there is visible soiling of the computer surface:

Features

- o First turn off the computer to prevent electric shock or damage to components.
- o Disconnect AC power.
- o Disconnect all powered external devices.
 - o Wipe the exterior of the computer with a soft, water-dampened cloth to remove the soil as needed.
- o The cloth should be of dry microfiber or a chamois (static-free cloth without oil), or static-free cloth wipes.
- o The cloth should be moist but not wet. Water dripping into the ventilation or other points of ingress can cause damage.
- o Please do not use fibrous materials, such as paper towels, as these can scratch the computer. Over time, dirt and cleaning agents can get trapped in the scratches.
 - o Allow the unit to air-dry before use or before additional cleaning with germicidal wipes.

If there is no visible soiling of the computer surface:

- o Launch the HP Easy Clean software application that came with your computer. This will disable the keyboard, display, and clickpad. (Or you could alternatively choose to put the computer in Sleep mode or turn off the computer).
- Next, use any of the following germicidal wipe formulations to safely disinfect all exposed surfaces of your computer including the keyboard, display, clickpad, and chassis. (Refer to the directions for use provided by the manufacturer of the wipes):
- o Formula 1
- o Benzyl-C12-18-alkyldimethyl ammonium chlorides: <0.1%
- o Quaternary ammonium compounds, C12-14-alkyl[(ethylphenyl)methyl]di methyl, chlorides: <0.1%
 - o Formula 2
- o 2-Butoxyethanol: <5%
- o Isopropanol: 10 20%
- o 2-Butoxyethanol: 5%
- o Benzyl-C12-18-alkyldimethyl ammonium chlorides: <0.5 %
- o Quaternary ammonium compounds,C12-18-alkyl [(ethylphenyl) methyl]dimethyl, chlorides: <0.5%
 - o Formula 3
- o Quaternary ammonium compounds, C12-18-alkyl [(ethylphenyl) methyl] dimethyl, chlorides: <0.5%
- o Benzyl-C12-18-alkyldimethyl ammonium chlorides: <0.5%
 - o Formula 4
- o Isopropyl alcohol: 55.0%
- o Alkyl dimethyl benzyl ammonium chlorides: 0.25%
- o Alkyl (68% C12, 32% C14) dimethyl ethylbenzyl ammonium chloride: 0.25%
 - o Formula 5
- o Isopropanol: 10 20%
- o Ethylene Glycol Monobutyl Ether (2-Butoxyethanol): 1-5%
- o Diisobutylphenoxyethoxyethyl dimethyl benzyl ammonium chloride: 0.1-0.5%

Features

- o Formula 6
- o Sodium hypochlorite 0.1-1%
 - o Formula 7
- o Cellulose: 10-30%
- o Ethyl alcohol: 0.10-1.00%
 - o Formula 8
- o Isopropyl alcohol: 30-40%
- o Water: 60 70%
 - Please do not use cleaners that contain any petroleum based materials such as benzene or thinner. These may damage the notebook.
 - o Do not close the computer until you've allowed it to completely air-dry.
 - o Once the surface is dry, the computer is ready for use again. Depending on how you readied the computer earlier, either exit the HP Easy Clean software, remove the computer from Sleep mode, or turn the computer back on to start using your computer again

Compatible Gloves

- o Touch on the screen and clickpad is tuned for support with bare hands and with the following list of surgical and exam gloves
- o McKesson Perry® Performance Plus Sterile Surgical Gloves
- o Smart Practice Neo Soothe Sterile Surgical Fitted Gloves
- o SKINTX Nitrile Exam Gloves
- o Precision Disposable Products Disposable Medical Exam Gloves
- o Medline SensiCare Exam Gloves
- o Kimberly Clark Safety Safeskin Exam Gloves

Technical Specifications

SYSTEM UNIT

Stand-Alone Power Requirements (AC Nominal Operating Voltage 190 Power) **Average Operating Power** Win 10 **Integrated Graphics** 6.78W **Discrete Graphics** 18W **Max Operating Power** Discrete < 65W **UMA < 45W Temperature** 32° to 95° F (0° to 35° C) (not writing optical) Operating 41° to 95° F (5° to 35° C) (writing optical) Non-operating -4° to 140° F (-20° to 60° C) **Relative Humidity Operating** 10% to 90%, non-condensing **Non-operating** 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperatur Shock Operating 40 G, 2 ms, half-sine Non-operating 200 G, 2 ms, half-sine **Random Vibration** Operating 0.75 grms Non-operating 1.50 grms Altitude (unpressurized) Operating -50 to 10,000 ft (-15.24 to 3,048 m) Non-operating -50 to 40,000 ft (-15.24 to 12,192 m) **Planned Industry Standard** UL Yes Certifications **CSA** Yes **FCC Compliance** Yes **ENERGY STAR®** Select models¹¹ **EPEAT®** Registered Gold in United States⁸ **ICES** Yes Australia / Yes **NZ A-Tick Compliance** CCC Yes **Japan VCCI Compliance** Yes KC Yes **BSMI** Yes **CE Marking Compliance** Yes **BNCI or BELUS** Yes CIT Yes **GOST** Yes Saudi Arabian Compliance Yes (ICCP)

Yes

SABS

UKRSERTCOMPUTER



Technical Specifications

- 11. Configurations of the HP Elitebook 840 G5 that are ENERGY STAR® qualified are identified as HP Elitebook 840 G5 ENERGY STA and on http://www.energystar.gov.
- 8. EPEAT® registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status b keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options.

DISPLAYS

Panel LCD 14 inch FHD (1920x1080)
Anti-Glare WLED UWVA 72% cg 700nits
eDP 1.3+PSR ultraslim Privacy

Outline Dimensions (W x H) 315.41x 196.14 max.

Active Area 309.312 x 173.988

Weight <225g max.

Diagonal Size 14.0"

Thickness 3.0mm max.
Interface eDP 1.4a
Surface Treatment IPS
Touch Enabled Yes

Contrast Ratio Sharing mode, 600:1 (typ.)

Privacy mode, 150:1 (typ.)

Refresh Rate 120Hz

Brightness Sharing mode, 700 nits (typ.)

Privacy mode, 350 nits (typ.)

Pixel Resolution 1920 x 1080 (FHD)

Format RGB
Backlight LED

Color Gamut Coverage Sharing mode, 72%

Privacy mode, 60%

Color Depth 6 bits + Hi FRC

Viewing Angle Sharing mode, CR > 10, L/R/U/D, 85/85/85/85 (typ.)

Privacy mode CR>2, L/R/U/D, 50/50/85/85 (typ.)

STORAGE1



Technical Specifications

SSD 128 GB 2280 M2 SATA-3 TLC Drive Weight 0.02 lb (10 g)

Capacity 128 GB

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfaceATA-8, SATA 3.0Maximum Sequential ReadUp To 520 MB/sMaximum Sequential WriteUp To 450 MB/sLogical Blocks250,069,680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Security Features DIPM; TRIM; DEVSLP

SSD 1 TB 2280 PCIe-3x4 NVMe

TLC SS

Drive Weight 0.02 lb (10 g)

Capacity 1 TB

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 2900 MB/sMaximum Sequential WriteUp To 2000 MB/sLogical Blocks2,000,409,263

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Security Features TRIM; L1.2

SSD 256 GB 2280 M2 PCle-3x4 SS

NVMe TLC

Drive Weight 0.02 lb (10 g)

Capacity 256 GB

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 2600 MB/sMaximum Sequential WriteUp To 900 MB/sLogical Blocks500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Security Features TRIM; L1.2

Technical Specifications

SSD 256 GB 2280 M2 SATA-3 Self Drive Weight Encrypted OPAL2 TLC Canacity

 Drive Weight
 0.02 lb (10 g)

 Capacity
 256 GB

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfaceATA-8, SATA 3.0Maximum Sequential ReadUp To 530 MB/sMaximum Sequential WriteUp To 515 MB/sLogical Blocks500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Security Features DIPM; TRIM; DEVSLP

256 GB 2280 PCIe NVMe Value Solid State Drive
 Drive Weight
 0.02 lb (10 g)

 Capacity
 256 GB

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 1700 MB/sMaximum Sequential WriteUp To 600 MB/sLogical Blocks500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Security Features TRIM; L1.2

SSD 360 GB 2280 PCIe-3x4 NVMe

TLC

 Drive Weight
 0.02 lb (10 g)

 Capacity
 360 GB

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 1700 MB/sMaximum Sequential WriteUp To 600 MB/sLogical Blocks703,282,608

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

Technical Specifications

SSD 512 GB 2280 M2 PCle-3x4 SS Drive Weight NVMe TLC

Drive Weight 0.02 lb (10 g)

Capacity 512GB

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 2600 MB/sMaximum Sequential WriteUp To 1400 MB/sLogical Blocks1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 512 GB 2280 M2 SATA-3 TLC

FIPS

Drive Weight 0.02 lb (10 g)

Capacity 512 GB

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfaceACS-3, SATA 3.2Maximum Sequential ReadUp To 530 MB/sMaximum Sequential WriteUp To 400 MB/sLogical Blocks1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features DIPM; TRIM; DEVSLP

SSD 512 GB 2280 PCIe-3x4 NVMe

Self Encrypted OPAL2 TLC

Drive Weight 0.02 lb (10 g)

Capacity 512 GB

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up To 2900 MB/s
Maximum Sequential Write Up To 1400 MB/s
Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

1. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

Technical Specifications

NETWORKING/COMMUNICATIONS

Data Rates

Intel® 802.11a/b/g/n/ac Wireless LAN Standards

(2x2) Wi-Fi® and Bluetooth® 4.2 Combo¹ IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac

Interoperability Wi-Fi® certified **Frequency Band** 802.11b/g/n

• 2.402 - 2.482 GHz

802.11a/n

• 4.9 - 4.95 GHz (Japan)

• 5.15 - 5.25 GHz

• 5.25 - 5.35 GHz

• 5.47 - 5.725 GHz

• 5.825 - 5.850 GHz

• 802.11b: 1, 2, 5.5, 11 Mbps

• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz,

40MHz, and 80MHz)

Modulation Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³

• IEEE and Wi-Fi® compliant 64 / 128 bit WEP encryption

for a/b/g mode only

• AES-CCMP: 128 bit in hardware

802.1x authentication

 WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

• IEEE 802.11i

 Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Output Power²

• 802.11b: +14dBm minimum

• 802.11g: +12dBm minimum

• 802.11a: +12dBm minimum

• 802.11n HT20(2.4GHz): +12dBm minimum

• 802.11n HT40(2.4GHz): +12dBm minimum

• 802.11n HT20(5GHz): +10dBm minimum

• 802.11n HT40(5GHz): +10dBm minimum

802.11ac VHT80(5GHz): +10dBm minimum

Technical Specifications

Power Consumption • Transmit mode 2.0 W

Receive mode 1.6 W

• Idle mode (PSP) 180 mW (WLAN Associated)

Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mW

Radio disabled 8 mW

Power Management ACPI compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express Half-MiniCard

Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm

 Weight
 Type 2230 : 2.8g

 Operating Voltage
 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF;

LED White - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy : 0~79 (1 MHz/CH)
Channels BLE : 0~39 (2 MHz/CH)

Data Rates andLegacy: 3 Mbps data rate; throughput up to 2.17 Mbps **Throughput**BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a

maximum transmit power of + 4 dBm for BR and EDR.

Technical Specifications

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Electrical Interface

USB 2.0 compliant

Bluetooth Software Supported

Microsoft Windows Bluetooth Software

Power Management

Certifications

Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles

Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 -Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

- 1. Wireless access point and Internet service is required. Availability of public wireless access point is limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Technical Specifications

HP lt4132 LTE/HSPA+ Technology/Operating

4G- Mobile Broadband bands

Module (Macan)¹

LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3) MHz,

850 (Band 5), 2600 (Band 7), 900 (Band 8) MHz,

800 (Band 20), 700 (Band 28) MHz.

HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz

Wireless protocol

standards

3GPP Release 10 LTE Specification CAT.4, 20MHz BW

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4

and MSC1 - MSC9

GPS Standalone, A-GPS (MS-B and LTO)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 150 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)

Maximum output power LT

LTE: 23 dBm HSPA+: 23.5 dBm

E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,600 mA (peak); 500 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 q

Dimensions 42 x 30 x 2.3 mm

(Length x Width x Thickness)

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices

Realtek 802.11b/g/n (2x2) Wi-Fi® and Bluetooth® 4.2 Combo¹

Wireless LAN Standards IEEE 802.11b

IEEE 802.11g IEEE 802.11n

Interoperability Wi-Fi® certified **Frequency Band** 802.11b/g/n⁷

• 2.402 - 2.482 GHz

Data Rates 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 07, (20MHz)

Technical Specifications

Modulation Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM,

• IEEE and Wi-Fi® compliant 64 / 128 bit WEP encryption for

a/b/g mode only AES-CCMP: 128 bit in hardware

802.1x authentication

WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

• IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX

WAPI

Network Architecture

Models

Security³

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

GPRS 900/850: 32.5 dBm

Roaming IEEE 802.11 compliant roaming between access points

Output Power² 802.11b: +16dBm minimum

> 802.11g: +14dBm minimum 802.11a: +14dBm minimum

• 802.11n HT20(2.4GHz): +13dBm minimum • 802.11n HT40(2.4GHz): +13dBm minimum

• 802.11n HT20(5GHz): +12dBm minimum

• 802.11n HT40(5GHz): +12dBm minimum

Transmit: 2.0 W (max) **Power Consumption**

Receive: 1.6 W (max)

Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 60 mW (WLAN unassociated)

Radio disabled: 30 mW

Power Management ACPI compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ 802.11b, 1Mbps: -94dBm maximum

> 802.11b, 11Mbps: -86dBm maximum 802.11g, 6Mbps: -88dBm maximum 802.11q, 54Mbps: -74dBm maximum 802.11a, 6Mbps: -86dBm maximum 802.11a, 54Mbps: -72dBm maximum 802.11n, MCS07: -69dBm maximum 802.11n, MCS15: -66dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded 2.4 GHz antennas are provided to the card to support WLAN

and Bluetooth communications

(Support Dual antenna or Single antenna, depend on platform requirement)

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm

Type 1630: 2.3 x 16.0 x 30.0 mm

Weight Type 2230: 2.8g

0r

Type 1630: 2g

Operating Voltage 3.3v +/- 9%

Technical Specifications

Temperature Operating: 14° to 158° F (-10° to 70° C)

Non-operating: -40° to 176° F (-40° to 80° C)

Humidity Operating: 10% to 90% (non-condensing)

Non-operating: 5% to 95% (non-condensing)

Operating: 0 to 10,000 ft (3,048 m)

Non-operating: 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF

LED White - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2 Compliant **Frequency Band** 2402 to 2480 MHz

Number of Available Legacy : 0~79 (1 MHz/CH)
Channels BLE : 0~39 (2 MHz/CH)

Data Rates andLegacy: 3 Mbps data rate; throughput up to 2.17 Mbps **Throughput**BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a

maximum transmit power of + 4 dBm for BR and EDR.

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Technical Specifications

HP It4210 LTE/HSPA+ 4G Mobile Broadband bands

Module (Pandora)1

Technology/Operating

LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower),

800 (Band 20), 700 (Band 28).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol

standards

3GPP Release 10 LTE Specification CAT.4, 20MHz BW WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

1xEVDO Release O, A and B.

E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4 and MSC1 -

MSC9

GPS Standalone, A-GPS (MS-A, MS-B and XTRA)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 150 Mbps (Download), 50 Mbps (Upload)

> DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

CDMA 1xRTT: 153.6 kbps (Download), 153.6 kbps (Upload) EVDO Rel.A: 3.1 Mbps (Download), 1.8 Mbps (Upload) EVDO Rel.B: 14.7 Mbps (Download), 5.4Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)

Maximum output power

LTE: 23 dBm HSPA+: 23.5 dBm 1xRTT/EVD0: 24dBm E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm

Maximum power consumption

Form Factor

HSPA+: 1,100 mA (peak); 800 mA (average) 1xRTT/EVDO: 1,000 mA (peak); 700 mA (average) E-GPRS: 2,800 mA (peak); 500 mA (average)

LTE: 1,200 mA (peak); 900 mA (average)

M.2, 3042-S3 Key B

Weight 6.2 g

Dimensions 42 x 30 x 2.3 mm

(Length x Width x Thickness)

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices

Near Field Communications Controller (optional)

Dimensions (L x W x H) Module 25 mm by 10 mm by 2.0 mm

NPC100 Chipset System interface I2C

Technical Specifications

NFC RF standards ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

NFC Forum Support Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD) ISO/IEC 14443 A Mode(1) ISO/IEC 14443 B ISO/IEC 15693

ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa

Jewel and Topaz cards

Card Emulation (PICC- ISO/IEC 14443 A VICC) Mode(1) ISO/IEC 14443 B and B'

MIFARE FeliCa

Frequency 13.56 MHz

NFC Modes Supported Reader/Writer, Peer-to-Peer Raw RF Data Rates 106, 212, 424, 848 kbps

Operating temperature0°C to 70°CStorage temperature-20°C to 125°CHumidity10-90% operating

5-95% non-operating

Supply Operating voltage 2.97 to 5.5 Volts **I/O Voltage** 1.8V or 3.3V

Power Consumption (Booster enable, VBAT= 3.3V, VCC_BOOST = 5V)

Mode Power Consumption, Typical

Polling 7.3 mA

Detected Test Tag Type 1 Total 283.8 mA

Net Module 236.8 mA

Detected Test Tag Type 2 Total 288.8 mA

Net Module 241.8 mA

Detected Test Tag Type 3 Total 287.7 mA

Net Module 240.7 mA

Detected Test Tag Type 4 Total 282.3 mA

Net Module 235.3 mA

Antenna Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is

external to module.

RFID Controller (optional)

Dimensions (L x W x H) Module 50 mm by 23 mm by 2.89 mm

Chipset SiM3U156+SiM3U154+AMS3911

Technical Specifications

System interface USB 2.0

NFC RF standards ISO/IEC 14443 A ISO/IEC 14443 B (In reading CSN) ISO/IEC 15693

ISO/IEC 18092 ECMA-340 NFCIP-1

NFC Forum Support Tag Type 1, Type 2, Type3 and Type 4 in reading CSN

Reader Mode 13.56MHz:

> ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa Topaz cards HID iClass ISO 125kHz: **HID Prox UID**

AWID UID CASI-RUSCO UID EM 410x UID Indana ASP/ASP+ UID

13.56MHz and 125kHz Frequency

NFC Modes Supported Reader

Raw RF Data Rates 106, 212 kbps -30°C to 70°C Operating temperature -40°C to 80°C Storage temperature **Humidity**

10-90% operating

5-95% non-operating

Supply Operating voltage 4.35 to 5.25 Volts

Power

Mode Power Consumption, Typical

Polling 75mA **Comunication** 85mA

Antenna 13.56MHz/125kHz combo antenna. Antenna connector, 0.5mm pitch, 16pin

connector FPC.

POWER

Technical Specifications

AC Adapter 65	Watt nPFC USB
type C	

 Dimensions
 74x74x28.5mm

 Weight
 unit: 245g +/- 10g

Input Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3

86.7% min at 115 Vac/ 230Vac @ 9V/3 88% min at 115 Vac/ 230Vac @ 10V/5 88% min at 115 Vac/ 230Vac @ 12V/5 89% min at 115 Vac/ 230Vac @ 15V/4 89% min at 115 Vac/ 230Vac @ 20V/3

Input frequency range 47 ~ 63 Hz

Input AC current 1.7 A at 90 VAC and maximum load

Output Output power 65W

 DC output
 5V/9V/10V/12V/15V/20V

 Hold-up time
 5ms at 115 Vac input

Output current limit <8.0A

Connector Duck head / duck head power cord, without Smart ID DC connector

Environmental DesignOperating temperature
32°F to 95°F (0° to 35°C)
Non-operating (storage)
-4°F to 185°F (-20°to 85°C)

Non-operating (storage) temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity5% to 95%Storage Humidity5% to 95%

EMI and Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class 1, S approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, C

CCC, NOM-1 NYCE.

MTBF - over 100,000 hours at 25°C ambient condition.

Technical Specifications

HP 65W Smart AC adapter

 Dimensions
 107.0x47.0x30.0mm

 Weight
 unit: 250g +/- 10g

Input Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230V

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.7 A at 90 Vac

Output Output power 65W

DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <11.0A

Connector 4.5mm Barrel Type

Environmental Design Operating temperature 32°F to 95°F (0°to 35°C)

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class 1, S approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, C

CCC, NOM-1 NYCE.

MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W EM Smart AC adapter

 Dimensions
 102x55x30mm

 Weight
 270q +/- 10q

Input Input Efficiency 87% min at 115V/230V

Input frequency range 47 to 63 Hz

Input AC current 1.7 A at 90 VAC and maximum load

Output DC output 65W(19.5V/3.33A)

Hold-up time 5 msec at 115 VAC input

Output current limit <11A, Over voltage protection- 29V m

shutdown

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords

Environmental Design Operating temperature 0° to 35° C

Non-operating (storage) -20° to 85° C

temperature

 Altitude
 0 to 5,000 m

 Humidity
 0% to 95%

 Storage Humidity
 0% to 95%

Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class 1, S approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, C

CCC, NOM-1 NYCE.

MTBF - over 200,000 hours at 25°C ambient condition.

Technical Specifications

Battery SS 3 Cell 50 WHr

Long Life -PL

Dimensions (H x W x L) L 278.7mm x W 76.3mm x H 7.1mm

Weight 193 +/- 10g

Cells/Type 3cell Lithium-Ion Polymer cell / P604883A1

Voltage 11.55V/

Energy Amp-hour capacity 4.113Ah/ 4.330Ah

Watt-hour capacity 50Wh

Operating (Charging) 0° to 50° C

Operating (Discharging) -10° to 60° C

Fuel Gauge LED N/A

Warranty 3 years

Optional Travel Battery

Available

Temperature

No

COUNTRY OF ORIGIN

China

Options and Accessories (sold separately and availability may vary by country)

	Description	Part #
Cases	HP Business Case	2SC66AA
	HP Slim Top Load	F3W15AA
	HP Exec Midnight 15.6" Backpack	1KM16AA
Docking	HP Thunderbolt Dock 120W G2	2UK37AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Dock G4	3FF69AA
	HP USB-C Mini Dock	1PM64AA
	HP UltraSlim Docking Station	D9Y32AA
Input/Output	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Slim USB Keyboard and Mouse	T6T83AA
	HP Wireless (Link-5) Keyboard	T6U20AA
	HP Wireless Premium Mouse	1JR31AA
	HP USB Premium Mouse	1JR32AA
	HP USB 3-Button USB Laser Mouse	H4B81AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP Slim Bluetooth Mouse	F3J92AA
	HP Elite Presenter Mouse	2CE30AA
	HP USB-C to USB-A Hub	Z6A00AA
	HP USB-C to DP	N9K78AA
	HP USB-C to VGA	N9K76AA
	HP HDMI to DVI	F5A28AA
	HP HDMI to VGA	H4F02AA
	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
Power	HP 65W Slim AC Adapter	H6Y82AA
	HP 65W Smart AC Adapter	H6Y89AA
Storage	HP USB External DVDRW Drive	F2B56AA
	HP 128 GB M2 TLC SATA-3 SSD (2280)	2JB96AA
Memory	HP 4 GB 2400MHz DDR4 Memory	Z4Y84AA
	HP 8 GB 2400MHz DDR4 Memory	Z4Y85AA
	HP 16 GB 2400MHz DDR4 Memory	Z4Y86AA
Security	HP Docking Station Cable Lock	AU656AA
	HP Keyed Cable Lock	TOY14AA

Options and Accessories (sold separately and availability may vary by country)

HP Keyed Cable Lock 10mm T1A62AA
HP Dual Head Keyed Cable Lock T1A64AA
HP 14.1 Privacy Filter V8Z57AA

UCC HP USB Collaboration Keyboard Z9N38AA

HP Wireless Collaboration Keyboard Z9N39AA
HP UC Wireless Mono Headset W3K08AA
HP UC Wireless Duo Headset W3K09AA
HP UC Speaker Phone K7V16AA

Displays HP HC240 24-inch Heathcare Edition Display Z0A71A4

HP HC270 27-inch Heathcare Edition Display

Z0A73A4

HP HC270cr 27-inch Healthcare Edition Display

1QW03A8 (for NA)

1QW03AA (for rest of the world)



Summary of Changes

Date of change:	Version History:		Description of change:
09/04/2018	V1 to V2	Update	Processors, Cleaning instructions sections
17/04/2018	V2 to V3	Update	Cleaning Instructions
30/04/2018	V3 to V4	Update	Weight and Dimensions
08/05/2018	V4 to V5	Added	Environmental tab
18/07/2018	V5 to v6	Added	Display

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